

## QUALITEK® 757 WATER SOLUBLE FLUX

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**Description**

Qualitek® 757 is a highly active organic flux developed for both leaded and lead-free automatic soldering applications and circuit board assembly. Qualitek 757 residues are easily removed using water cleaning systems. 757 displays excellent foaming characteristics but may also be applied by spray, dip, brush or wave methods. 757 was formulated to reduce fumes during use.

Main Features

- ❑ Excellent wettability
- ❑ No excessive fumes or smoke
- ❑ Compatible with Lead-Free & Leaded Solder Systems

**Technical Data**

<b>Flux Classification</b>	<b>Specification</b>	<b>Test Method</b>
<b>Color and Appearance</b>	ORH1	IPC-J-STD-004B
<b>Copper Mirror</b>	Light Amber Liquid	
<b>Corrosion Test (Cleaned)</b>	Complete removal of copper film	IPC-TM-650 2.3.32
<b>SIR (Cleaned)</b>	Pass	IPC-TM-650 2.6.15
<b>Specific Gravity (g/cm<sup>3</sup>) @ 25°C</b>	3.25 x 10 <sup>10</sup> ohms	IPC-TM-650 2.6.3.3
<b>Solids Content, % Wt.</b>	0.844 ± 0.01	
<b>pH Value</b>	11.5 ± 1.0	
<b>% Halides</b>	2.00 – 3.00	
	2.0	

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## Applications

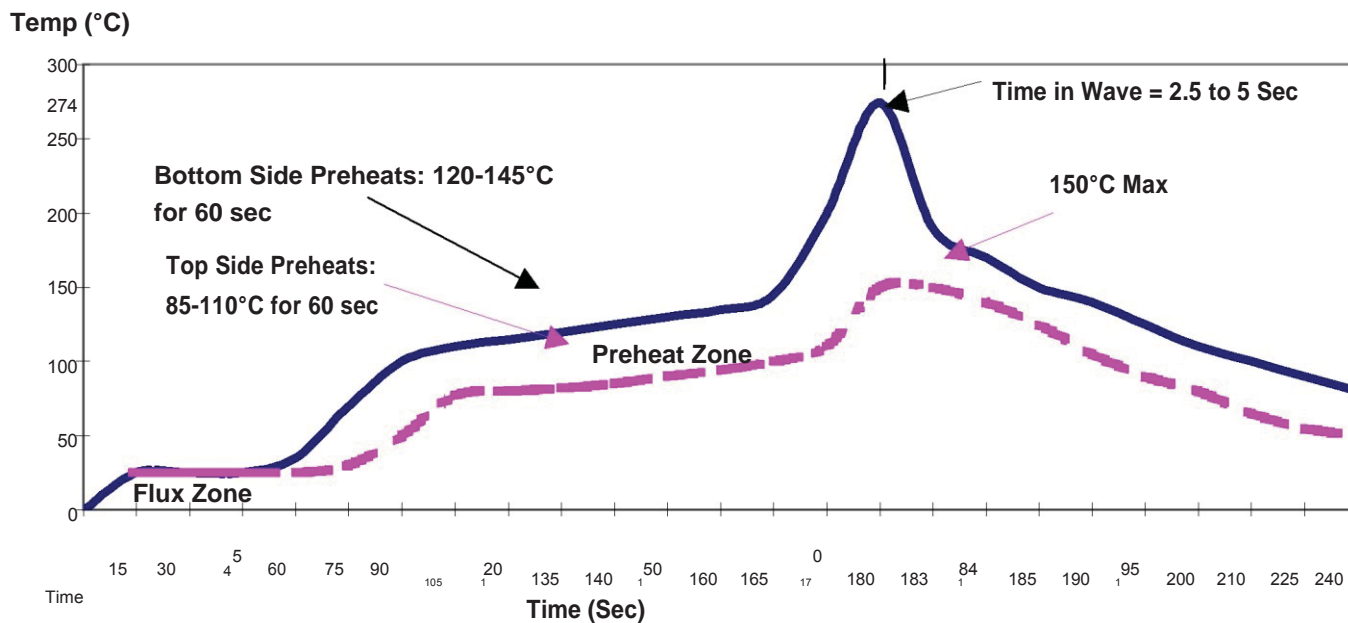
### Flux Application

For mass wave soldering of OSP and plated circuit boards, spray, foam or wave fluxing can be utilized to apply this flux. Flux deposition density and uniformity are critical to successful use of low solids water soluble flux. If foam fluxing, the foam fluxer should be supplied with compressed air, which is free of oil and water. The flux tank should be full at all times. The surface of the flux should be 1-½ inches above the top of the flux aerator, or flux stone. Pressure should then be adjusted to produce the optimum foam height with a fine uniform foam head. After fluxing, an air knife should be used to remove excessive flux from the assembly.

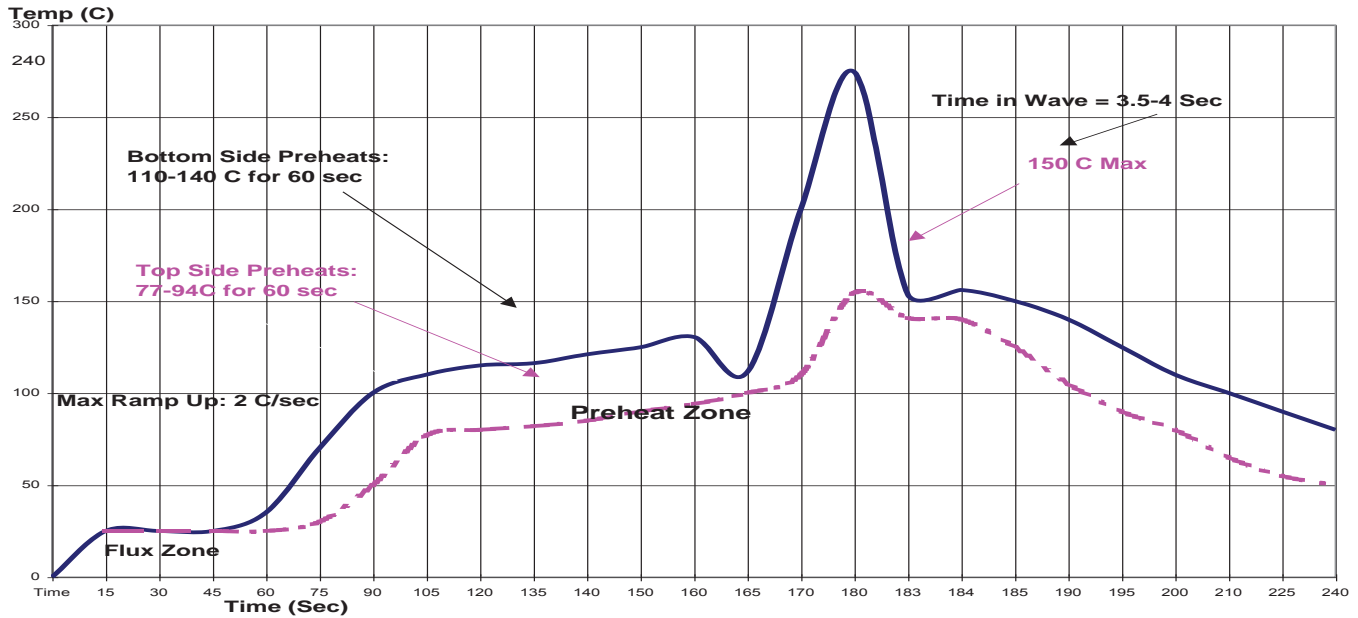
Uniformity of the spray flux coating can be visually checked by running a tempered glass plate (usually supplied by machine manufacturer) through the spray and preheat sections, and inspected before going across the wave.

OPERATING PARAMETERS		TYPICAL LEVEL
Amount of flux		Foam, Wave: 1000-2000 µg/in <sup>2</sup> solids Spray: 750-1500 µg/in <sup>2</sup> solids
Foam Fluxing Parameters		
	Foam Stone Pore Size	20-50 µm
	Flux Level Above Stone	1-1 ½ inches (25-40mm)
	Chimney Opening	3/8-1/2 inch (10-13 mm)
	Air Pressure	1-2 psi
Top Side Preheat Temperature		190-230 °F (85-110 °C)
Bottom Side Preheat Temperature		65 °F (35 °C) higher than topside
Conveyor Speed		4-6 feet/minute(1.2-1.8 meters/minute)
Contact Time in the Solder (including Chip & Lambda)		2.5-4.5 seconds
Solder Pot Temperature		
	Sn96.5/Ag3.5	500-530 °F (260-276 °C)
	Sn95/Ag5	536-565 °F (280-296 °C)
	Sn99.3/Cu0.7	510-530 °F (265-276 °C)
	<b>SnAgCu</b>	520-530 °F (271-276 °C)
	Sn95/Sb5	536-565 °F (280-296 °C)

### TYPICAL Lead Free Wave Solder Profile (SNAGCU)



**TYPICAL Leaded Wave Solder Profile (Sn63/Pb37)**



**Process Control**

Control of flux during use is necessary to assure a consistent amount of flux is applied to assemblies. Monitoring and controlling specific gravity is recommended for maintaining the proper flux concentration. Density (specific gravity) can be performed using a hydrometer. Control of the flux can be achieved with 700T thinner to maintain fluxing activity.

Over time debris and contaminants may accumulate in the flux reservoir. Therefore, periodically replacing the flux and cleaning the reservoir is recommended for consistent performance and minimizing debris build-up.

#757 Flux	
Specific Gravity	Thinner Required Fl oz/ga
0.843	0
0.846	6
0.850	12
0.853	17
0.856	22
0.859	26

**Flux Residues and Cleaning**

As with all water-soluble fluxes, post-soldering cleaning is required. Residues can be easily removed with both hot and cold water, thus; no neutralizer is needed. De-ionized water should be used in the final rinse for cleanliness results beyond MIL-28809A. Spray pressures should be maintained at 20-30 psi and conveyor speed of 3-6 ft. /min.

## **Storage & Shelf Life**

757 Liquid Flux should be stored in a 65-80°F environment away from direct heat and flame. Shelf life is 2 years from date of manufacture.

## **Packaging**

757 Water Soluble Liquid Flux is available in

- 1 Gallon/1 Liter containers
- 5 Gallon/5 Liter containers
- 55 Gallon/20 Liter containers

## **Disposal**

757 contains hazardous ingredients therefore the flux should be disposed of in accordance with federal, state and local authority requirements.

Qualitek® is a brand of Qualitek International, Inc.